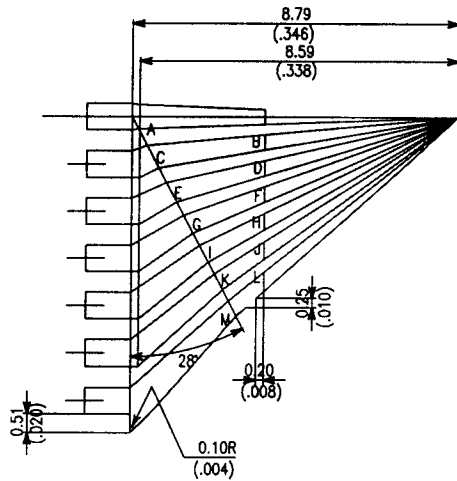


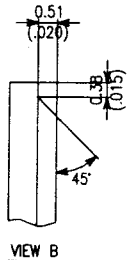
NOTES

1. MATERIALS
 CERAMIC TO OPAQUE, 90-94% Al_2O_3
 SOLDER GLASS TO BE 7583.
 MAX PULLBACK TO BE 0.25(.010)
 FROM CERAMIC EDGE.
 DIE ATTACH AREA TO BE Au 120
 MICROINCH MIN.
 LEAD FRAME TO BE ALLOY 42 OR
 EQUIVALENT WITH ALUMINIUM
 BOND PADS, 100 MICROINCH THICK
 AND 35 MILS IN LENGTH WITH NO
 PULL BACK.
3. THERE WILL BE NO UNSUPPORTED
 BOND PADS GRATER THAN 0.25(.010)
4. ADJACENT BOND PADS MUST BE
 CO-PLANAR WITHIN 0.15(.006)
 TOTAL CO-PLANARITY NO GRATER
 THAN 0.25(.010).
5. THERE WILL BE NO NICKS, CUTS
 OR GLASS IN THE BOND RADIUS
6. MINIMUM INTERNAL METAL
 SEPARATION OTHER THAN BOND FINGERS
 TO BE 0.15(.006)

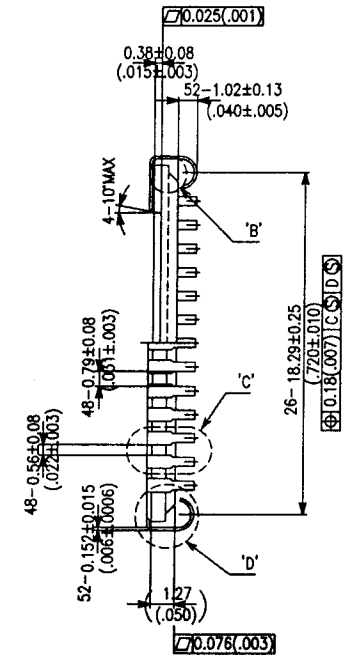
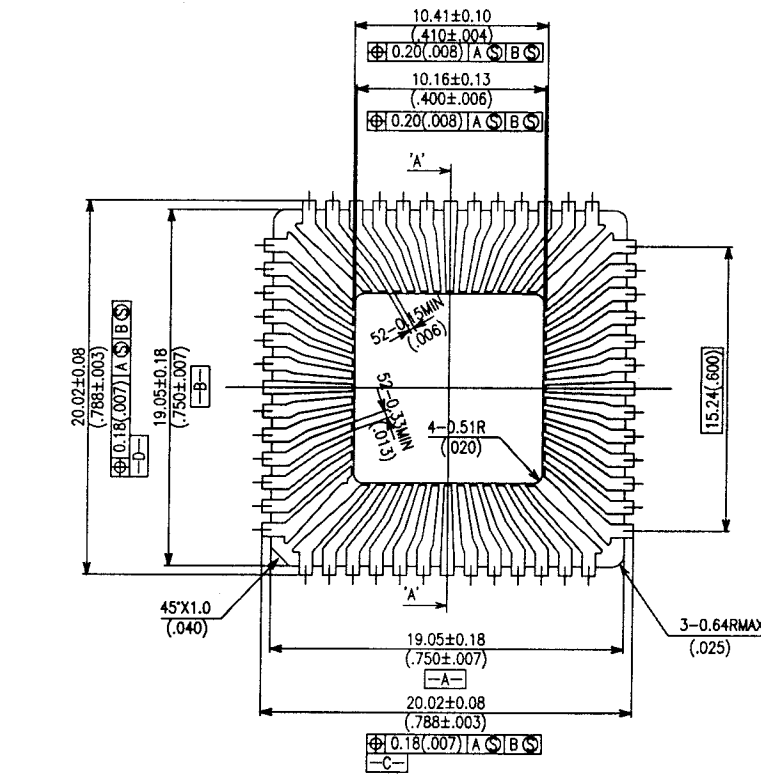
No.	ANGLE
A	2.18°
B	5.25°
C	9.58°
D	12.59°
E	16.78°
F	19.68°
G	23.70°
H	26.47°
I	30.24°
J	32.83°
K	36.36°
L	38.76°
M	42.02°



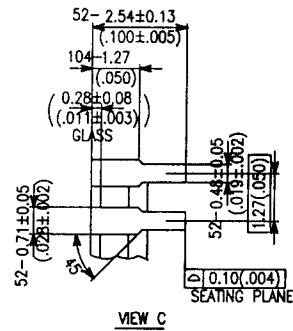
LEAD TIP DETAIL



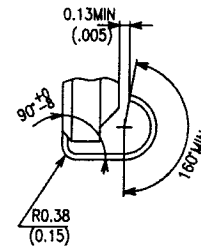
VIEW B



SECTION A-A

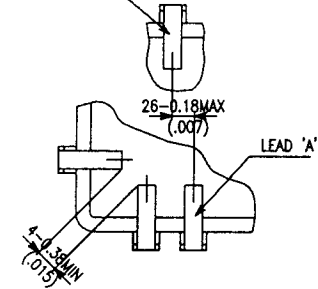


VIEW C



VIEW D

LEAD 'B' OPPOSITE SIDE
OF PACKAGE FROM LEAD 'A'



JEDEC TYPE

MODIFICATIONS	CHANGE				DATE	DRAWN	CHECKED	APPROVED	NAME 52LD QUAD CERPAC'J'(750-400)	SCALE 5:1	MATERIAL	TOLERANCES: UNLESS OTHERWISE SPECIFIED	DRAWN	CHECKED
	CHANGE												APPROVED	DATE
													APPROVED	DATE
													FEB.06'89	
											KYOCERA CORPORATION	KYOTO JAPAN	DWG No.	QC-052215-J-1